MIPI Alliance and USB 3.0 Promoter Group Announce Availability of SuperSpeed USB Inter-Chip Specification

SSIC optimizes SuperSpeed USB and M-PHY™ for internal mobile device applications

MOBILE ASIA EXPO, SHANGHAI – June 20, 2012 – MIPI Alliance and the USB 3.0 Promoter Group today announced the completion of the SuperSpeed USB Inter-Chip (SSIC) specification. The specification defines a chip-to-chip USB based internal interconnect for mobile devices as well as other platforms. SSIC offers MIPI Alliance’s M-PHY™ high bandwidth and low power capabilities combined with SuperSpeed USB performance enhancements.

The M-PHY™ interface, a high speed serial interface, targets up to 2.9 Gbps per lane with scalability up to 5.8 Gbps per lane and offers a low pin count and exceptional power efficiency. SuperSpeed USB offers a 5 Gbps signaling rate, up to 10 times faster than Hi-Speed USB (USB 2.0), enhanced protocol and power management and backward compatibility with the existing USB device and software model.

“MIPI Alliance is focused on enabling enhanced performance within mobile devices,” said Joel Huloux, MIPI Alliance Chairman of the Board. “With SSIC uniting the M-PHY physical layer with the SuperSpeed USB protocol layer, manufacturers and developers can benefit from the new mobile, low-power technology.”

“SSIC opens the door for a broad range of USB-enabled functions to migrate into a huge mobile market,” said Brad Saunders, USB 3.0 Promoter Group Chairman. “This chip-to-chip interface may also find its way back into the PC ecosystem for its low-power benefits.”

The USB 3.0 Promoter Group developed the SSIC specification and has transitioned the specification’s management to the USB-IF. The USB 3.0 Promoter Group is now accepting adopters of the SSIC specification. To download both the SSIC specification and USB 3.0 adopter agreement, visit http://www.usb.org/developers/docs/.

Member Support

“SSIC is designed to leverage existing USB 3.0 software stack investments, while providing extremely low power consumption for next generation devices,” said Billy Anders, Microsoft Windows Group Manager. “Combined with the Windows 8 and Windows RT mobile broadband class driver, SSIC provides systems with an industry standard and low-power mobile broadband inter-chip solution while meeting the performance demands of today’s 4G LTE devices and mobile networks.”
“SSIC represents an important milestone in the convergence of low-power mobile technology and proven PC technology,” said Joel Huloux, Director, Standardization and Industry Alliances for ST-Ericsson. “ST-Ericsson, as a member of both MIPI Alliance and the USB 3.0 Promoter Group, has actively contributed to make this happen and believes that SSIC will encounter wide market adoption.”

“SSIC offers mobile device developers the opportunity to take advantage of USB 3.0’s gigabit speeds with minimal power consumption,” said Ed Bard, senior director of product marketing for IP at Synopsys. “Our participation in the SSIC working group enabled us to make valuable contributions to the development of the specification. To help validate the specification, Synopsys developed the SSIC proof-of-concept demonstration system, which included the Synopsys® DesignWare® USB 3.0 IP and HAPS® FPGA-based prototyping system.”

About SuperSpeed USB
SuperSpeed USB brings significant performance enhancements to the ubiquitous USB standard, while remaining compatible with the billions of USB-enabled devices currently deployed in the market. SuperSpeed USB delivers up to 10x the data transfer rate of Hi-Speed USB, as well as improved power efficiency. SuperSpeed USB offers effortless audio/video streaming, music and photos at your home, office, car and anywhere in between.

About the USB 3.0 Promoter Group
The USB 3.0 Promoter Group, comprised of Hewlett-Packard Company, Intel Corporation, Microsoft Corporation, Renesas Electronics, ST-Ericsson and Texas Instruments, developed the USB 3.0 specification that was released in November 2008. In addition to maintaining and enhancing this specification, the USB 3.0 Promoter Group develops specification addendums to extend or adapt its specifications to support more platform types or use cases where adopting USB 3.0 technology will be beneficial in delivering a more ubiquitous, richer user experience.

About the USB-IF
The non-profit USB Implementers Forum, Inc. was formed to provide a support organization and forum for the advancement and adoption of USB technology. USB-IF facilitates the development of high-quality, compatible USB devices through its logo and compliance program recognized around the globe and promotes the benefits of USB and the quality of products that have passed compliance testing. Further information, including postings of the most recent product and technology announcements, is available by visiting the USB-IF website at www.usb.org

About MIPI M-PHY
M-PHY is a physical layer serial interface technology with high bandwidth capabilities, developed specifically for mobile device applications. The first version of the specification was released in 2009 and has received wide usage throughout the industry.

About MIPI Alliance
MIPI Alliance is a global, collaborative organization comprised of companies that span the mobile ecosystem and are committed to defining and promoting interface specifications for mobile devices. MIPI Specifications establish standards for hardware and software interfaces which drive new technology and enable faster deployment of new features and services. For more information, go to www.mipi.org

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